



“Improving Yields” Technology Seminar



SEMINAR AGENDA

Tuesday, April 2nd

Morning Session (8:30-12p)

8:30: “The Role of Particle Size in Reducing Head in Pillow Defects” (Dr. Neil Poole, Henkel Technologies)

9:10: “Stencil Guidelines for today’s Technologies” (Todd Ramsay, Bob McGlynn, Tropical Stencil)

9:40: “Optimizing the Print Process for 0.3mm pitch WLCSPs” (Dr. Denis Barbini, Universal Instruments)

10:20: Break

10:15: “Process Improvement through accurate 3D measurement” (Thorsten Niermeyer, Koh Young Technology)

11:00: Hands-On in Koh Young Truck (in Rialto parking lot)

12:00: Lunch

Afternoon Session (1-4pm) Follows same format as the am session

TRC is pleased to announce its “Improving Yields Technology Seminar” to be held at the Hilton-Rialto in Melbourne on April 2nd. We have organized two half-day free seminars, including lunch. Please sign up at your earliest convenience as space is limited for each session.

The seminars will run 3.5 hours and include one hour of “hands-on” inside the Koh Young truck.

Besides the economic factors that have an impact on our businesses every day, we are continually tasked with new challenges from our customers. The key objective of this seminar is to provide you with better tools and ideas to combat the process challenges on your factory floor associated with solder-related defects. Solder-related defects for SMT assembly typically represents 60-80% of all defects. What are you doing to lower this number in your factory? Are you using a multitude of solder pastes in your plant due to various processes and customer requirements? With Pb-free challenges and processing at much higher temperatures, are you really certain that your profiles are in-spec or are you running a “one size fits all” process where field rejects might come back later? What about hidden joint inspection..QFNs and uBGAs..package on package and other device technologies that are driving you towards different solder paste powder sizes, stencil treatments or other process changes?

We can’t “fix everything” in a 4 hour session, however we hope that by bringing together some of the industry’s most well respected experts, that you might have an opportunity to bend their ears about your specific issues and challenges. Dr. Denis Barbin of Universal Instruments’ Advanced Process Lab, Dr. Neil Poole, Sr. Applications and Chemist for Henkel Technologies, Thorsten Niermeyer of Koh Young with more than 25 years experience with 2D and 3D AOI and SPI inspection technologies, and Bob McGlynn/Todd Ramsey of Tropical Stencil with numerous years of experience in QFNs, stencil coating technologies and more will speak to topics aimed to increase your process windows while addressing latest challenges.

We look forward to your attendance. Please visit the link here to sign-up as space is limited; mention the am or pm session and whether you will join us for the lunch which overlaps both seminars.

<http://3dinspectionontour.com/>



TRC has hosted a series of Advanced Process Technology seminars in the past and they have helped customers solve many assembly process challenges. The theme of this seminar is “You Don’t know what you Don’t know” and we have organized speakers to address many of today’s challenges, how to increase your process windows, and maintaining an “in-spec” process while dealing with even more NPIs. Hope to see you there!

Location: Hilton-Rialto
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